

SN75ALS191 双路差分线路驱动器

1 特性

- 符合或超出 ANSI 标准 EIA/TIA-422-B 和 ITU 建议 V.11 的要求
- 设计在 20Mbaud 或更高速率下运行
- TTL 和 CMOS 输入兼容性
- 由 5V 单电源供电运行
- 输出短路保护
- 经过改进可替代 μ A9638

2 应用

- 工厂自动化
- ATM 和点钞机
- 智能电网
- 交流和伺服电机驱动器

3 说明

SN75ALS191 是一款双路高速差分线路驱动器，可满足 ANSI 标准 EIA/TIA-422-B 和 ITU 建议 V.11 的要求。输入是 TTL 和 CMOS 兼容输入，并具有输入钳位二极管。肖特基二极管钳位晶体管可更大限度地减少传播延迟时间。该器件由单个 5V 电源供电并采用 8 引脚封装。

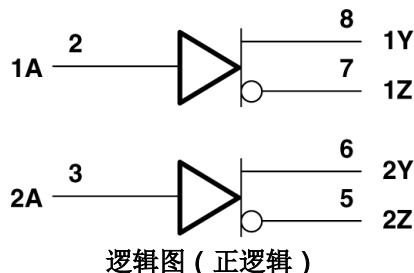
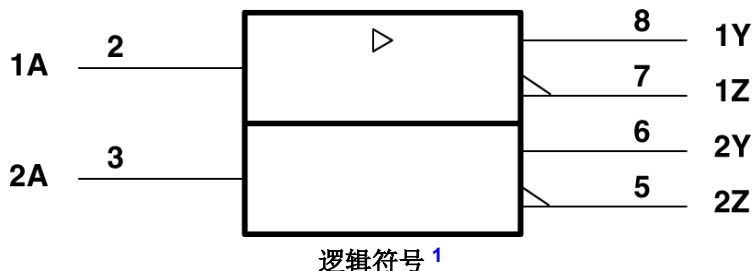
SN75ALS191 的工作温度范围是 0°C 至 70°C。

封装信息

器件型号	封装 ⁽¹⁾	封装尺寸 ⁽²⁾
SN75ALS191	P (PDIP , 8)	9.81mm × 9.43mm
	D (SOIC , 8)	4.9mm × 6mm
	PS (SOP , 8)	6.2mm × 7.8mm

(1) 有关更多信息，请参阅节 10。

(2) 封装尺寸 (长 × 宽) 为标称值，并包括引脚 (如适用)。



¹ 此符号符合 ANSI/IEEE 标准 91-1984 和 IEC 出版物 617-12。



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4 Pin Configuration and Functions

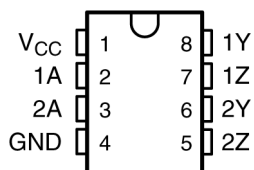


图 4-1. D or P Package
(Top View)

表 4-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
1Z	7	O	Inverting Output of Differential Driver on Channel 1
1Y	8	O	Non-Inverting Output for Differential Driver on Channel 1
1A	2	I	Single Ended Data Input for Channel 1
GND	4	GND	Device Ground
2A	3	I	Single Ended Data Input for Channel 2
2Y	6	O	Non-Inverting Output for Differential Driver on Channel 2
2Z	5	O	Inverting Output of Differential Driver on Channel 2
V _{CC}	1	P	5V Power Supply Positive Terminal Connection

(1) Signal Types: I = Input, O = Output, I/O = Input or Output, P = Power, GND = Ground.

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage, see ⁽²⁾		7	V
V_I	Input voltage		7	V
	Continuous total dissipation	See <i>Dissipation Rating</i> table		
T_A	Operating free-air temperature range	0	70	°C
	Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds		260	°C
T_{stg}	Storage temperature range	–65	150	°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values except differential output voltage (V_{OD}) are with respect to network ground terminal.

5.2 Dissipation Rating

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING
D	725mW	5.8mW/°C	464mW
P	1000mW	8mW/°C	640mW

5.3 Recommended Operating Conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.75	5	5.25	V
High-level input voltage, V_{IH}	2			V
Low-level input voltage, V_{IL}			0.8	V
High-level output current, I_{OH}			–50	mA
Low-level output current, I_{OL}			50	mA
Operating free-air temperature, T_A	0		70	°C

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		D	P	PS	UNIT
		8-Pins			
R _{θJA}	Junction-to-ambient thermal resistance	116.7	84.3	89.5	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	56.3	65.4	46.2	°C/W
R _{θJB}	Junction-to-board thermal resistance	63.4	62.1	50.7	°C/W
ψ _{JT}	Junction-to-top characterization parameter	8.8	31.3	23.5	°C/W
ψ _{JB}	Junction-to-board characterization parameter	62.6	60.4	60.3	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP ⁽¹⁾	MAX	UNIT
V_{IK}	Input clamp voltage	$V_{CC} = 4.75V$,	$I_I = -18mA$			-1	-1.2	V
V_{OH}	High-level output voltage	$V_{CC} = 4.75V$,	$V_{IH} = 2V$,	$I_{OH} = -10mA$	2.5	3.3		V
		$V_{IL} = 0.8V$		$I_{OH} = -40mA$	2			
V_{OL}	Low-level output voltage	$V_{CC} = 4.75V$, $I_{OL} = 40mA$	$V_{IH} = 2V$,	$V_{IL} = 0.8V$,			0.5	V
$ V_{OD1} $	Differential output voltage	$V_{CC} = 5.25V$,	$I_O = 0$				$2 V_{OD2}$	V
$ V_{OD2} $	Differential output voltage	$V_{CC} = 4.75V$ to $5.25V$, See 图 6-1			2			V
$\Delta V_{OD} $	Change in magnitude of differential output voltage ⁽²⁾						± 0.4	V
V_{OC}	Common-mode output voltage ⁽³⁾						3	V
$\Delta V_{OC} $	Change in magnitude of common-mode output voltage ⁽²⁾						± 0.4	V
I_O	Output current with power off	$V_{CC} = 0$		$V_O = 6V$		0.1	100	μA
				$V_O = -0.25V$		-0.1	-100	
				$V_O = -0.25V$ to $6V$			± 100	
I_I	Input current	$V_{CC} = 5.25V$,	$V_I = 5.5V$				50	μA
I_{IH}	High-level input current	$V_{CC} = 5.25V$,	$V_I = 2.7V$				25	μA
I_{IL}	Low-level input current	$V_{CC} = 5.25V$,	$V_I = 0.5V$				200	μA
I_{OS}	Short-circuit output current ⁽⁴⁾	$V_{CC} = 5.25V$,	$V_O = 0$		-50		-150	mA
I_{CC}	Supply current (all drivers)	$V_{CC} = 5.25V$,	No load,	All inputs at 0V	32		40	mA

(1) All typical values are at $V_{CC} = 5V$ and $T_A = 25^\circ C$.

(2) $|V_{OD}|$ and $|V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

(3) In ANSI Standard EIA/TIA-422-B, V_{OC} , which is the average of the two output voltages with respect to ground, is called output offset voltage, V_{OS} .

(4) Only one output at a time should be shorted, and duration of the short circuit should not exceed one second.

5.6 Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 5V$

PARAMETER		TEST CONDITIONS			MIN	TYP ⁽¹⁾	MAX	UNIT
$t_{d(OD)}$	Differential-output delay time	$C_L = 15pF$,	$R_L = 100\Omega$,	See 图 6-2		3.5	7	ns
$t_{t(OD)}$	Differential-output transition time					3.5	7	ns
	Skew					1.5	4	ns

(1) Typical values are at $T_A = 25^\circ C$.

6 Parameter Measurement Information

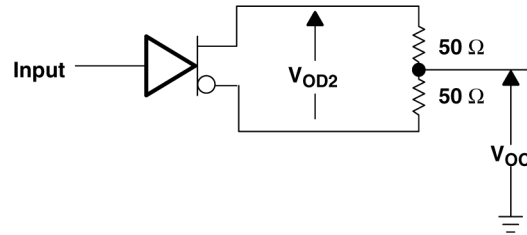
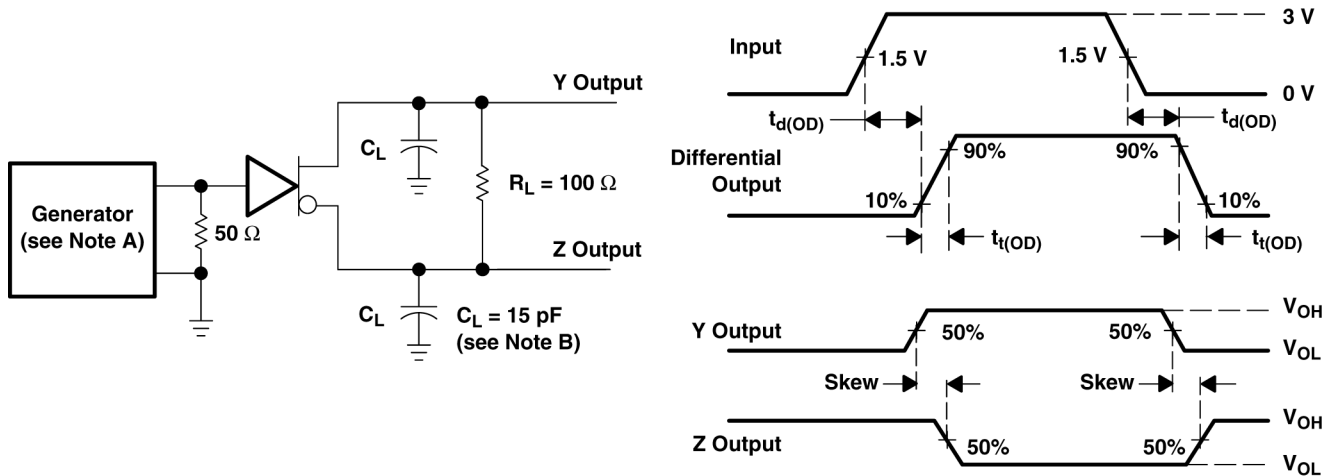


图 6-1. Differential and Common-Mode Output Voltages



TEST CIRCUIT

VOLTAGE WAVEFORMS

- A. The input pulse generator has the following characteristics: $Z_O = 50 \, \Omega$, $PRR \leq 500 \text{ kHz}$, $t_w = 100 \text{ ns}$, $t_r \leq 5 \text{ ns}$.
 B. C_L includes probe and jig capacitance.

图 6-2. Test Circuit and Voltage Waveforms

7 Detailed Description

7.1 Device Functional Modes

表 7-1. Function Table (Each Driver)

INPUTS A ⁽¹⁾	OUTPUTS	
	Y	Z
H	H	L
L	L	H

(1) H = high level, L = low level, Z = high impedance

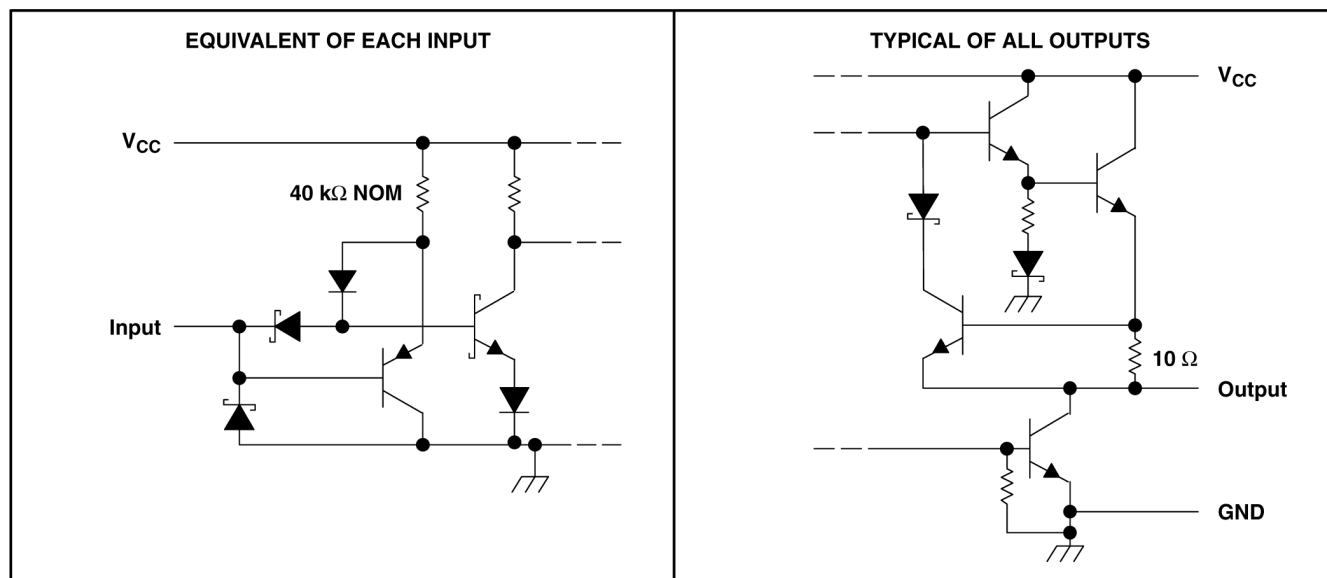


图 7-1. Schematics of Inputs and Outputs

8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

8.2 支持资源

TI E2E™ [中文支持论坛](#) 是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [使用条款](#)。

8.3 Trademarks

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8.4 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.5 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

9 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision B (May 1995) to Revision C (March 2024)	Page
• 更改了整个文档中的表格、图和交叉参考的编号格式.....	1

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN75ALS191D	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	0 to 70	75A191
SN75ALS191DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75A191
SN75ALS191P	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	75ALS191
SN75ALS191PSR	Active	Production	SO (PS) 8	2000 LARGE T&R	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	0 to 70	V191

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS191DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS191DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS191PSR	SO	PS	8	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN75ALS191PSR	SO	PS	8	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS191DR	SOIC	D	8	2500	353.0	353.0	32.0
SN75ALS191DR	SOIC	D	8	2500	340.5	336.1	25.0
SN75ALS191PSR	SO	PS	8	2000	356.0	356.0	35.0
SN75ALS191PSR	SO	PS	8	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN75ALS191P	P	PDIP	8	50	506	13.97	11230	4.32
SN75ALS191PE4	P	PDIP	8	50	506	13.97	11230	4.32



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



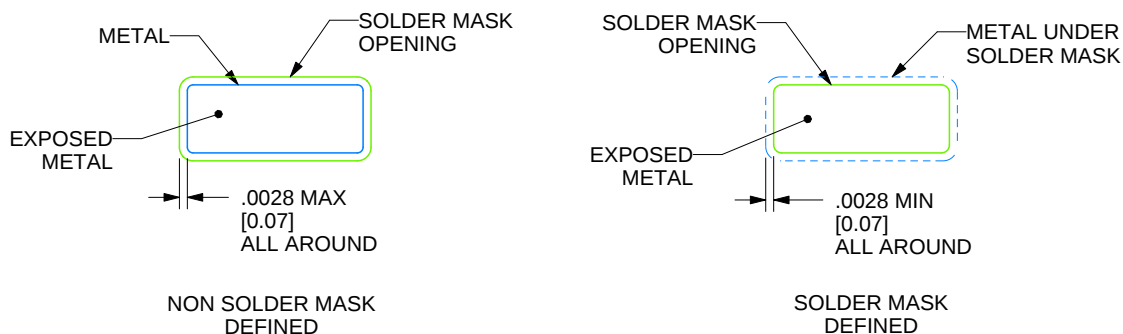
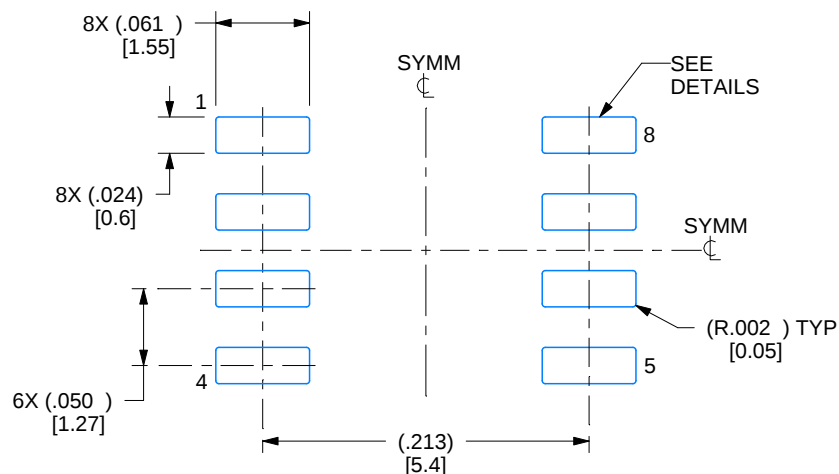
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

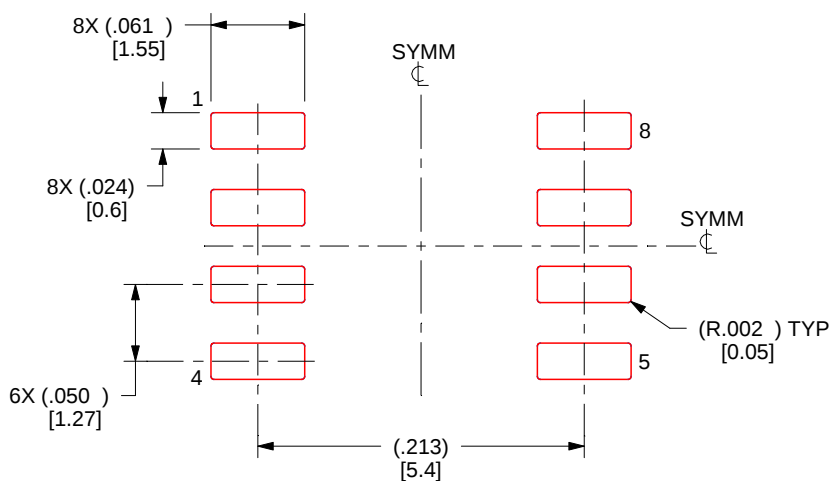
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

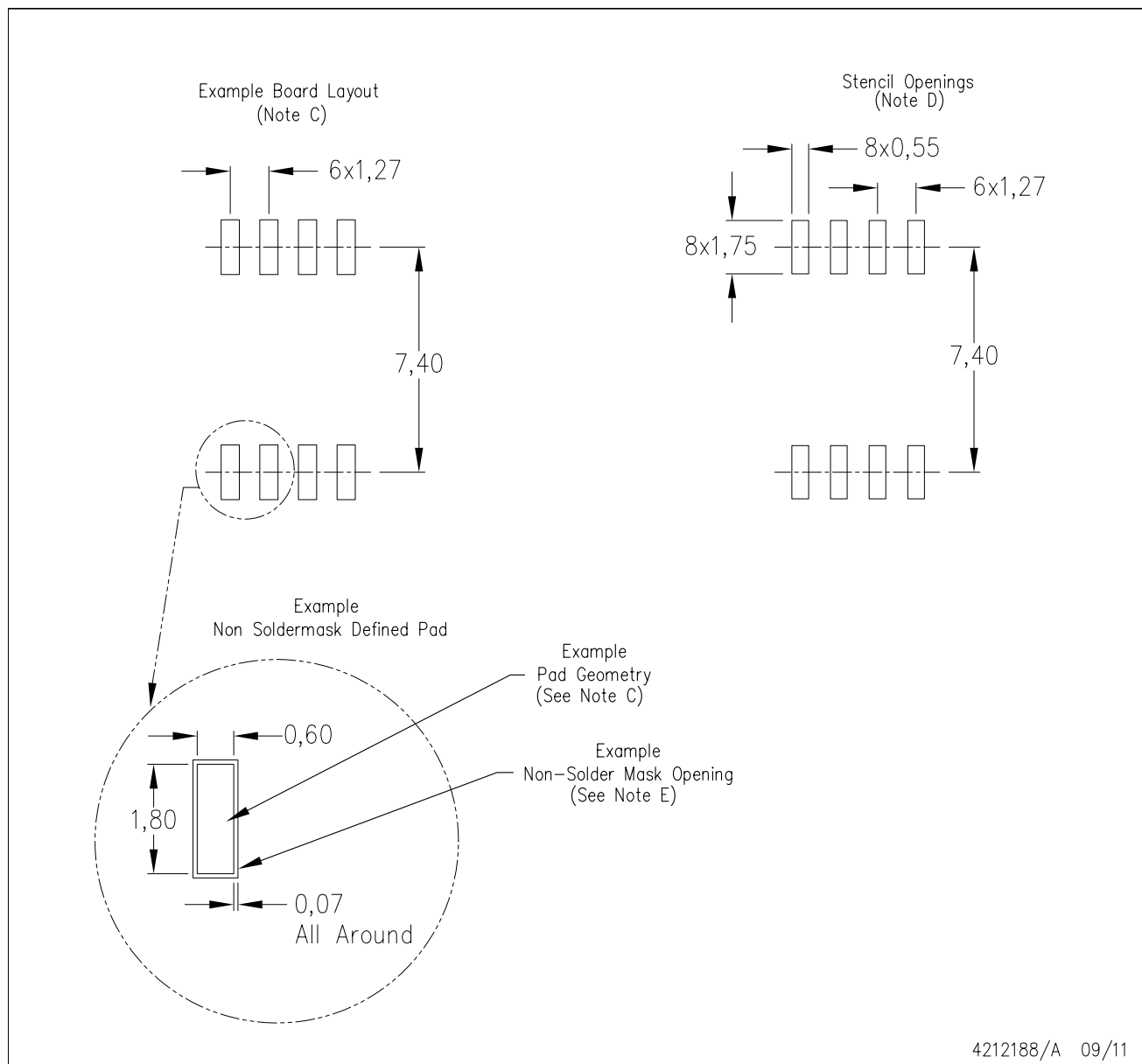


4040063/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

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